

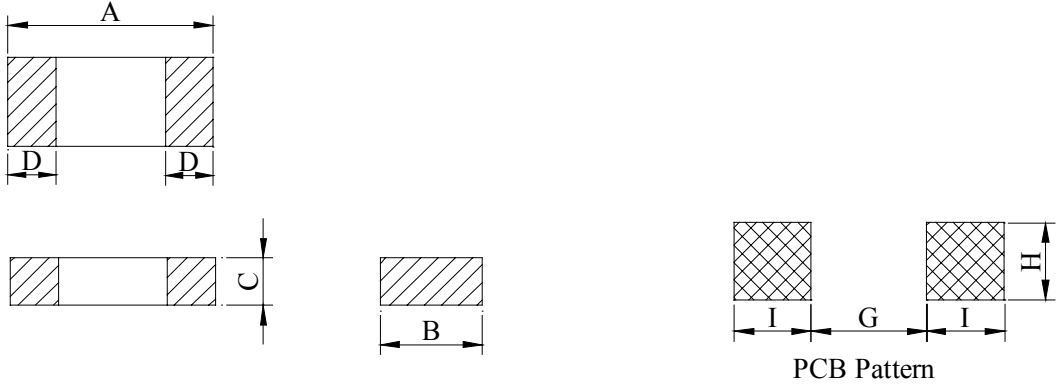
# SPECIFICATION FOR APPROVAL

REF :

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PROD. NAME	MULTILAYER CHIP BEAD	ABC'S DWG NO.	MU1608□□□□5□
		ABC'S ITEM NO.	

**. CONFIGURATION & DIMENSIONS :**



Unit : m/m

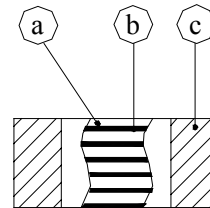
Series	A	B	C	D	G	H	I
MU1608	1.60±0.15	0.80±0.15	0.80±0.15	0.30±0.20	0.7	0.7	0.7

**. SCHEMATIC DIAGRAM :**



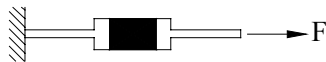
**. MATERIALS :**

- a . Body : Ferrite
- b . Internal conductor : Silver or Ag / Pd
- c . Terminal electrode : Ag/Ni/Sn (Lead content 100ppm max.)
- d . Remark : Lead content 1000ppm max. include ferrite



**. GENERAL SPECIFICATION :**

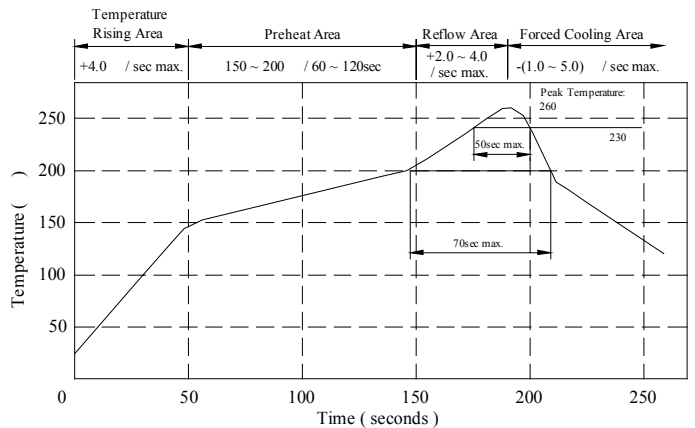
- a . Storage temp. : -40 ---- +105
- b . Operating temp. : -25 ---- +85
- c . Terminal Strength :



Type	F ( kgf )	time ( sec )
MU1608	0.5	30±5

- d . Solderability : Preheat : 150±25°C for 60 seconds  
 Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent  
 Solder temp. : 260±5  
 Flux : Rosin  
 Dip time : 4±1 seconds

Peak Temp : 260 max.  
 Max time above 230 : 50sec max.  
 Max time above 200 : 70sec max.



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. ELECTRICAL CHARACTERISTICS :

DWG No.	Impedance ( $\Omega$ )	Z Test Freq. ( MHz )	RDC ( $\Omega$ ) max.	Ir ( mA ) max.
MU1608050Y5□	3 ~ 9	100	0.05	2000
MU1608100Y5□	5 ~ 15	100	0.05	2000
MU1608300Y5□	30.0±25%	100	0.05	2000
MU1608600Y5□	60.0±25%	100	0.10	500
MU1608121Y5□	120.0±25%	100	0.20	300
MU1608221Y5□	220.0±25%	100	0.30	300
MU1608301Y5□	300.0±25%	100	0.35	200
MU1608471Y5□	470.0±25%	100	0.40	200
MU1608601Y5□	600.0±25%	100	0.50	200
MU1608102Y5□	1000.0±25%	100	0.60	200

1). □ : Packaging Information... A: Bulk B: Taping Reel

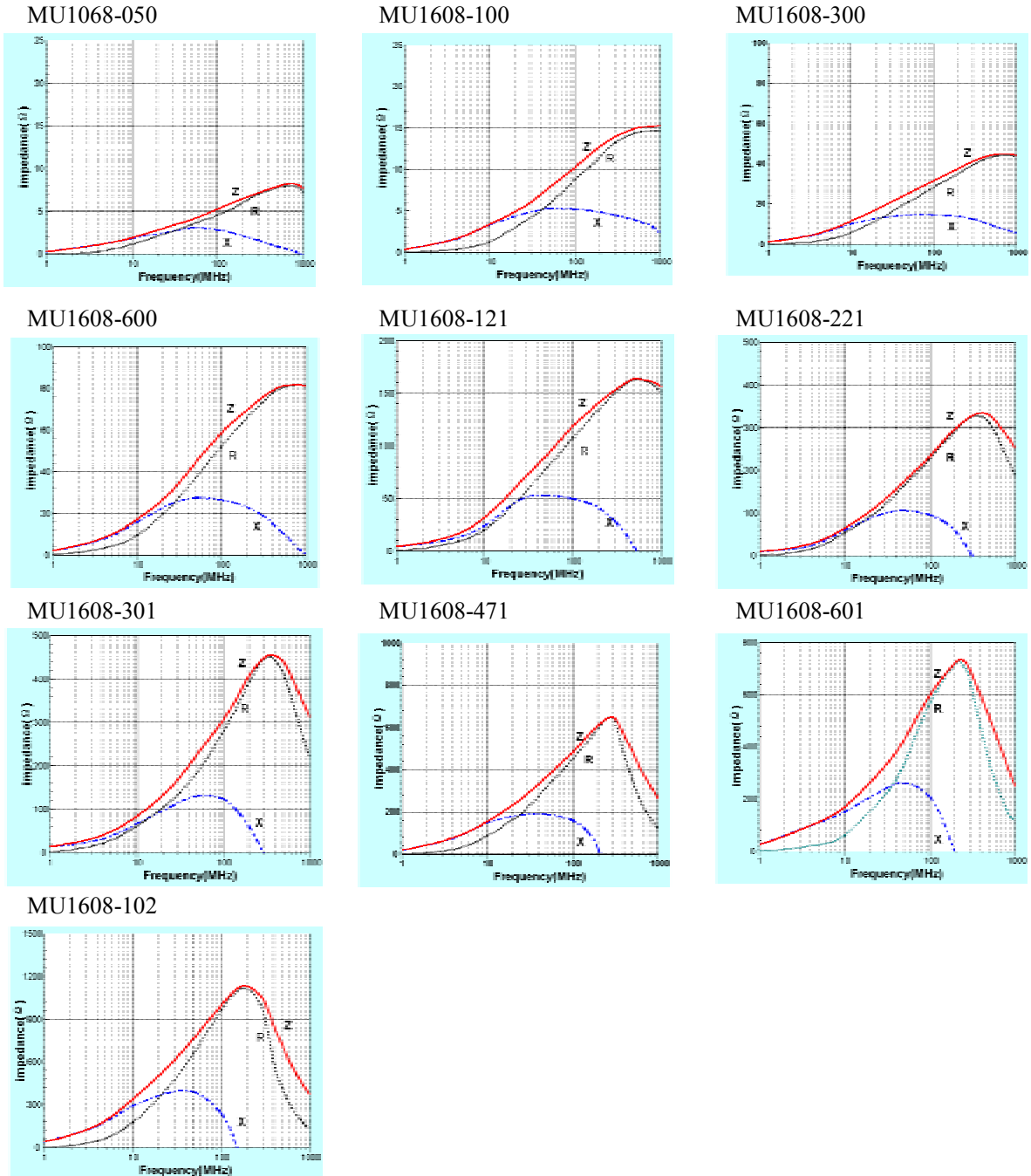
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. IMPEDANCE VS. FREQUENCY CHARACTERISTICS :



AE-001A

# SPECIFICATION FOR APPROVAL

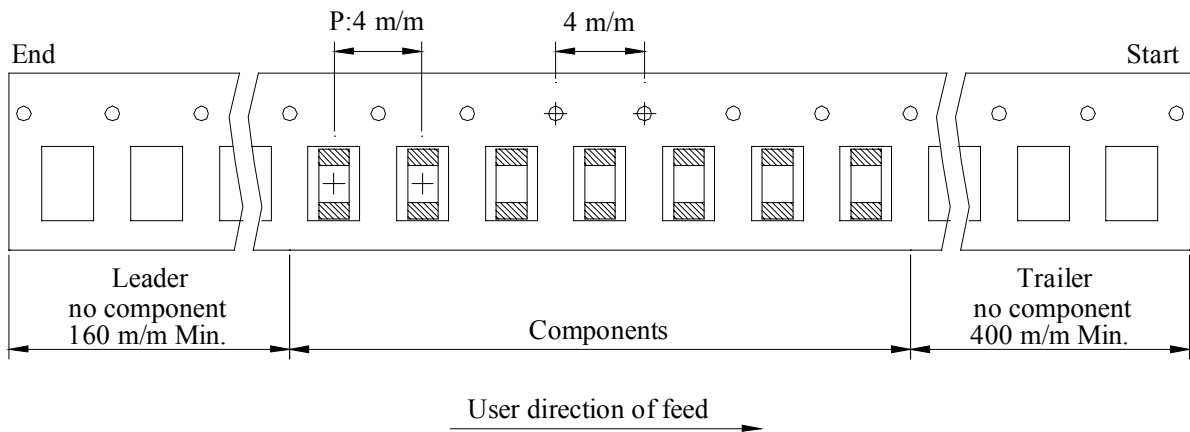
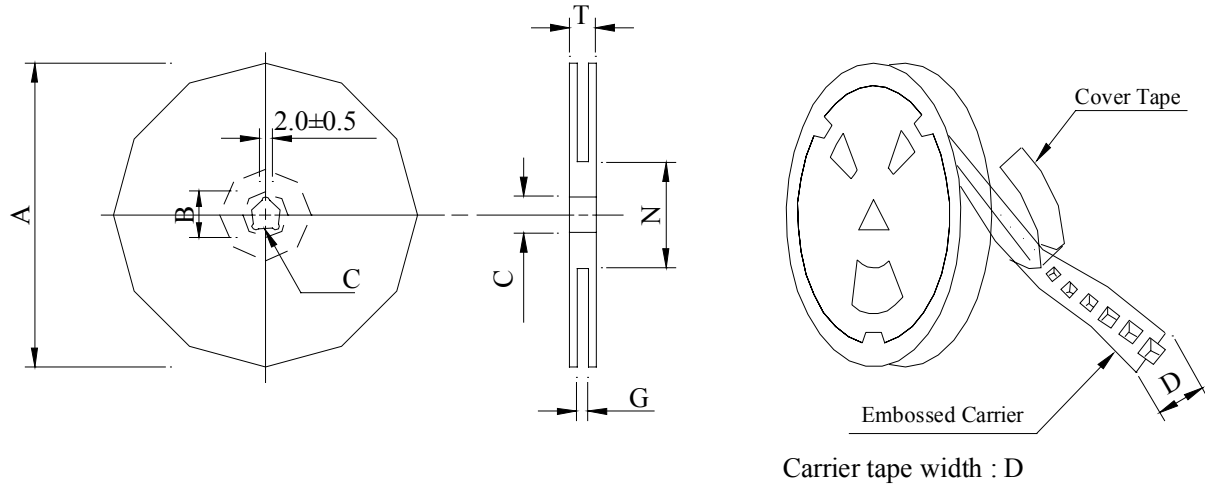
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		ABC'S ITEM NO.	

## PACKAGING INFORMATION

### ( 1 ) Configuration



### ( 2 ) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 <sup>+0</sup>	50 <sup>-0</sup>	12.5

### ( 3 ) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY(pcs)	G.W. (Kg)	Size (cm)
MU1608	4,000	90	07 - 08	200,000	7.0	41 x 39 x 22

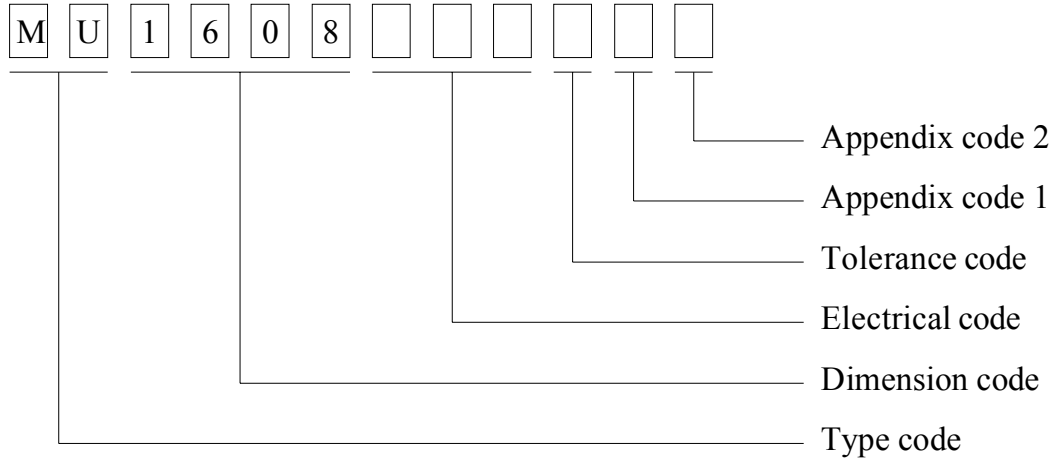
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. DWG EXPRESSION :



- Appendix code 1 : S : Standard products
- A K , M R , T Z : Special products
- L : Standard Lead Free products
- 1 ~ 9 : Special Lead Free products

Appendix code 2 :

Code	Inner package	Inner package Q'TY	Remark
A	Empty	Empty	
B	T / R ( Reel package )	4000 pcs	